

LIDLESS CHIP PACKAGE EFFECTIVELY HAVING CO-PLANAR FRAME AND SEMICONDUCTOR DIE SURFACES

Abstract

A “lidless” integrated circuit package includes a support member that is arranged to support at least part of a load placed on the integrated circuit package. The support member has or is connected to a flexible support device that is in supportive contact with the load and that is designed to flex dependent on a position of the support member. The flexible support device substantially ensures that a plane of the surface of the flexible support device and a plane of a surface of a semiconductor die of the integrated circuit package are co-planar, thereby leading to a desirable load distribution within the integrated circuit package.

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